

FIG. 1(B) SEQUENTIAL FORMATION OF INSULATING LAYER 1016 AND

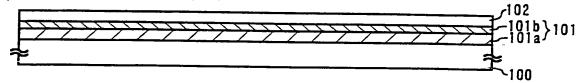
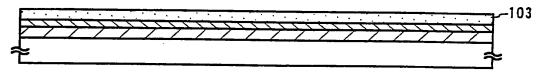


FIG. (C) CRYSTALLIZATION



FORMATION OF ACTIVE LAYER AND GATE INSULATING FILM FIG. 1(D)

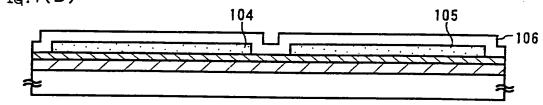
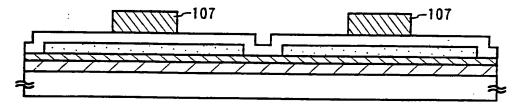


FIG. (E) FORMATION OF GATE WIRING



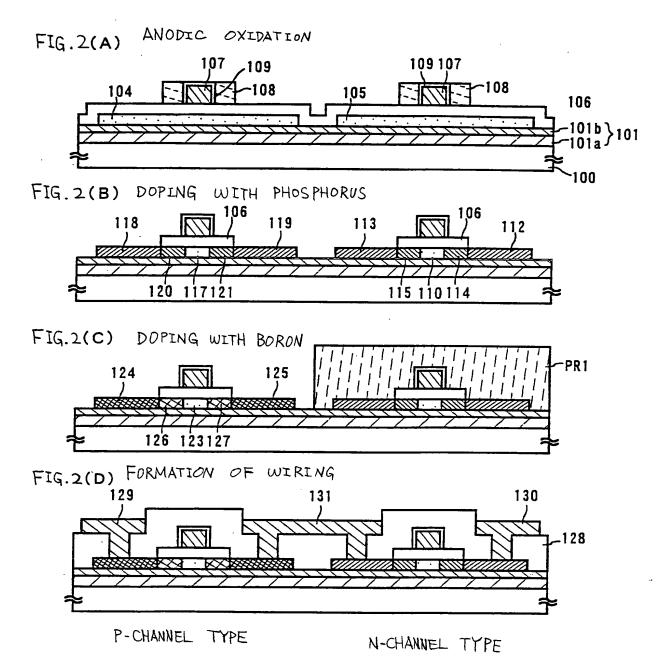
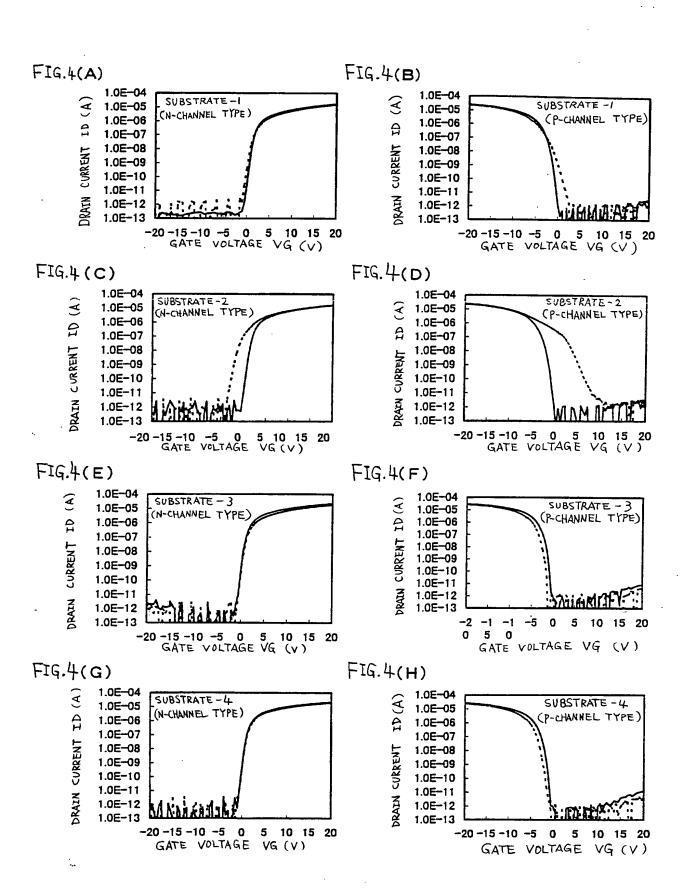


FIG.3

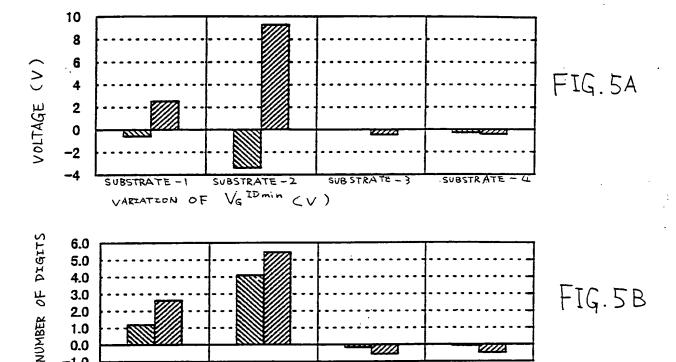
		SUBSTRATE - 1 SI	JBSTRATE - 2 SUBSTRATE - 3	SUBSTRATE-
FLOW RATE OF RAW MATERIAL GAS	SiH4	4	10	15
	N₂O	400	20	20
	NH3	0	100	200
HEAT TREATMENT		CONDUCTED N	O NO	No
COMPOSITION RATIO (atomic %)	N	7. 0	24. 0	44. 1
	0	59. 5	26. 5	6. 0
	Si	32. 0	33. 0	34. 4
	Н	1. 5	16. 5	15. 5
REFRACTIVE INDEX		1. 45	66 1. 7468	1. 7975

FILM FORMING CONDITIONS AND PHYSICAL PROPERTIES OF INSULATING LAYER (SILICON OXIDE NITRIDE LAYER) 10/9



1.0 0.0 -1.0 & N-CHANNEL TYPE (L/W = 5.6/7.5 Mm) (L/w = 5.6/7.5 mm) P-CHANNEL TYPE

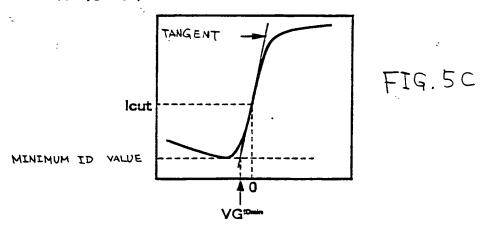
SUBSTRATE-4



CHANGE OF NUMBER OF DIGITS OF I cut

X STRESS CONDITIONS 150°C, I hour, VG: 20V (N-CHANNEL TYPE), -ZOV (P-CHANNEL TYPE), VD=VS= 0 V

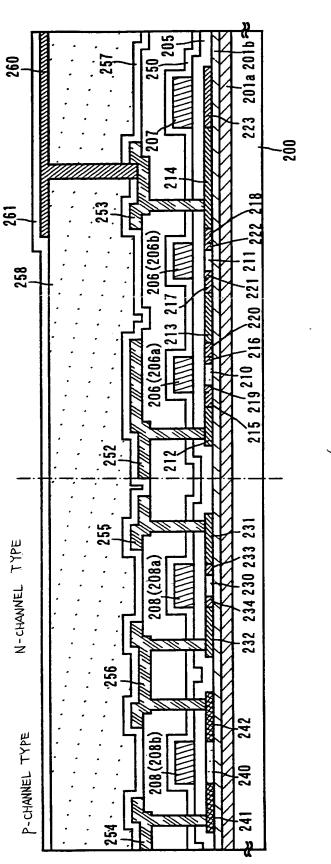
SUBSTRATE-3



ID-VG CHARACTERISTIC CURVE

DRIVER CIRCUIT (CMOS CIRCUIT)

PIXEL MATRIX CIRCUIT



FORMATION OF UNDERLYING FILM, ACTIVE LAYER AND GATE INSULATING FILM

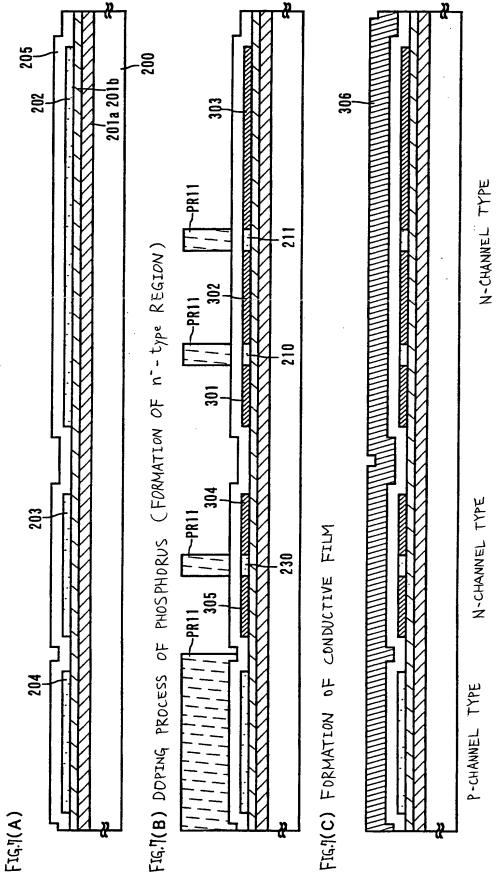


FIG.8(A) DOPING WITH BORON (FORMATION OF P+-TYPE REGION)

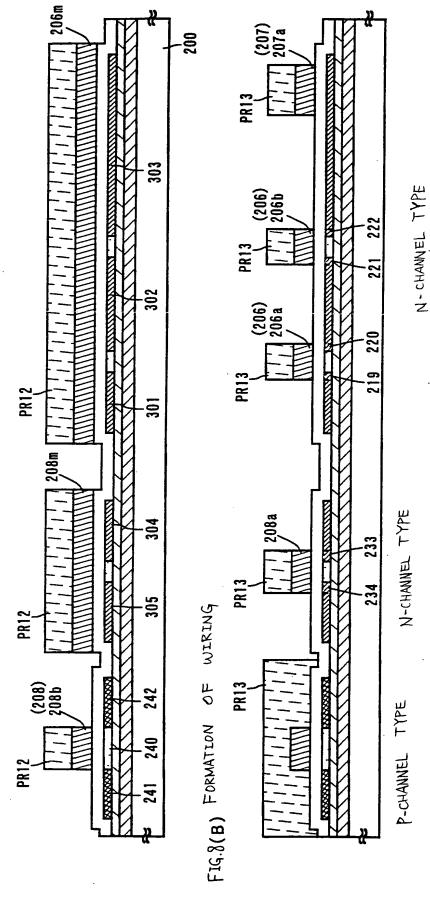
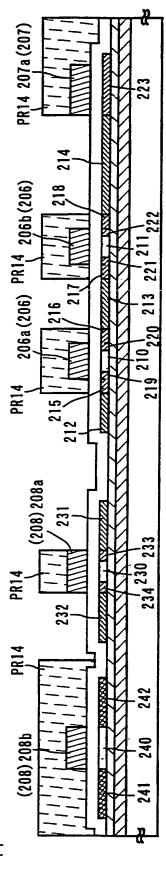
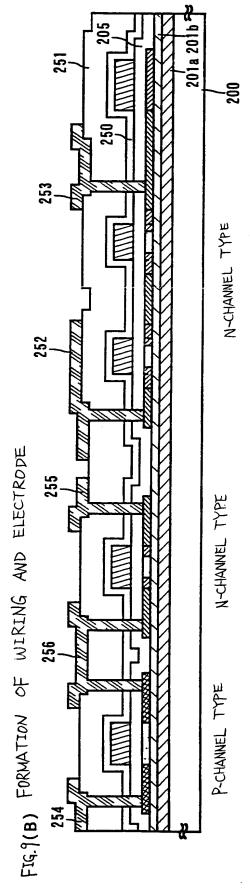
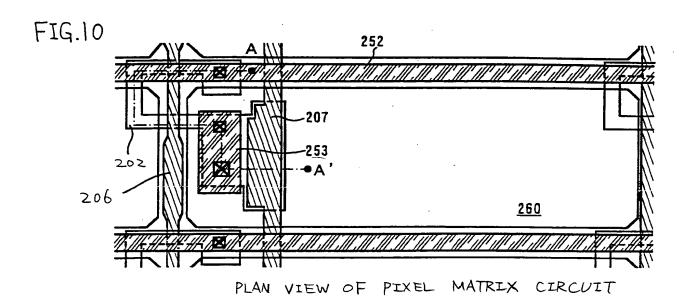
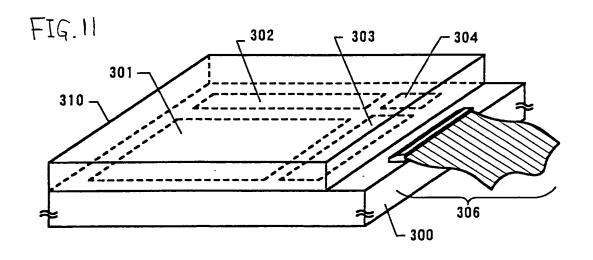


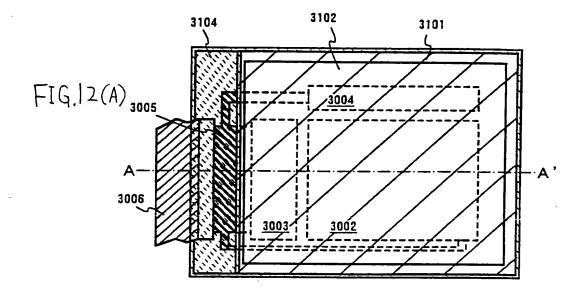
FIG. 9(A) DOPING WITH PHOSPHORUS (FORMATION OF N+-TYPE REGION)

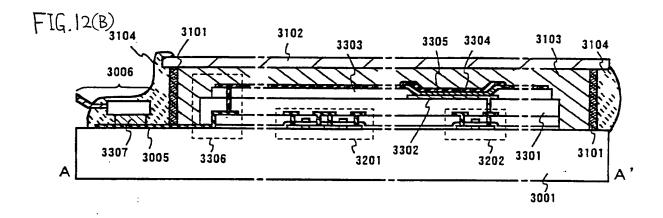


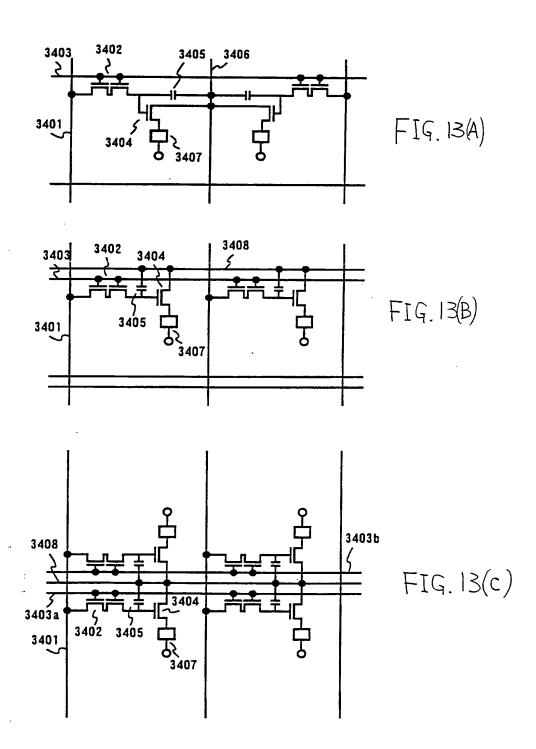


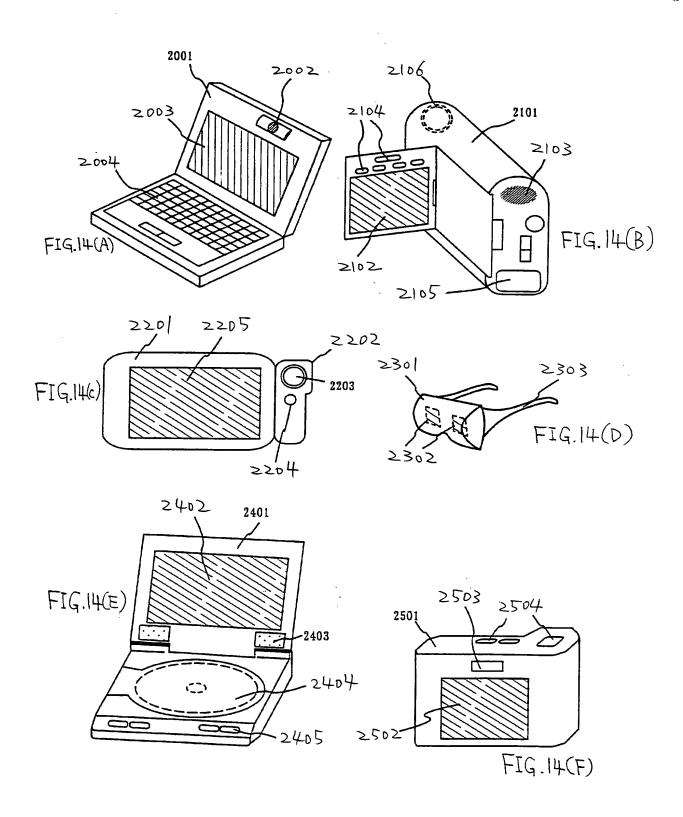


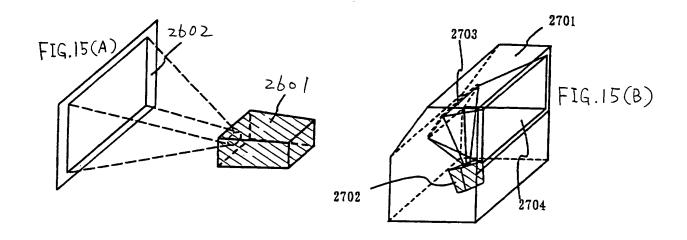












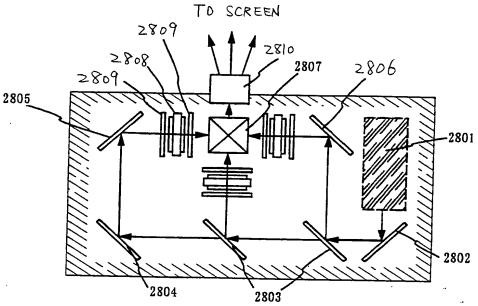
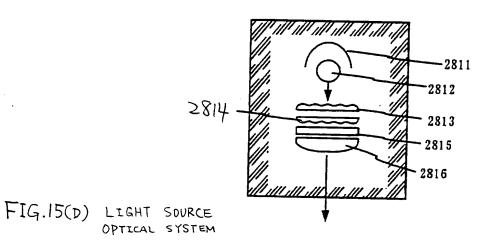
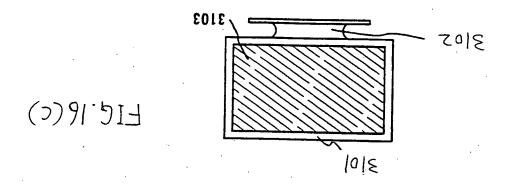


FIG. 15(C) PROJECTION UNIT (THREE-LENS TYPE)





900E 500E 700E 100E 100E

FIC 16 (B)

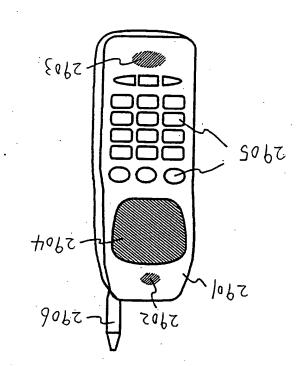


FIG.16(A)